



Material Content Data Sheet



Sales Product Name	SAK-XC2336B-40F66L AA			Issued		29. August 2013		
MA#	MA001126142							
Package	PG-LQFP-64-6			Weight*		372.45 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	28.688	7.70	7.70	77025	77025
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		87	
	non noble metal	zinc	7440-66-6	0.130	0.03		349	
	non noble metal	iron	7439-89-6	2.600	0.70		6980	
	non noble metal	copper	7440-50-8	105.558	28.34	29.08	283417	290833
wire	noble metal	gold	7440-57-5	1.862	0.50	0.50	4999	4999
encapsulation	organic material	carbon black	1333-86-4	1.096	0.29		2943	
	plastics	epoxy resin	-	29.600	7.95		79474	
	inorganic material	silicondioxide	60676-86-0	188.562	50.64	58.88	506278	588695
leadfinish	non noble metal	tin	7440-31-5	4.066	1.09	1.09	10916	10916
plating	noble metal	silver	7440-22-4	1.611	0.43	0.43	4325	4325
glue	plastics	epoxy resin	-	2.161	0.58		5802	
	noble metal	silver	7440-22-4	6.482	1.74	2.32	17405	23207
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com